



Creative Materials, Inc.
12 Willow Road
Ayer, MA 01432

T 978.391.4700
F 978.391.4705

126-19**ELECTRICALLY CONDUCTIVE DIE ATTACH EPOXY ADHESIVE**

DESCRIPTION: 126-19 is a one component, heat cured, and non-bleeding, silver-filled epoxy adhesive. The 126-19 is syringe dispensable, stencilable, and pin-transferrable and may be used for die bonding or for making electrical and mechanical attachments on electrical components and devices. Unlike typical heat curing systems, this product always results in excellent conductivity and is less sensitive to handling and ambient conditions and can be used in applications alongside heat sensitive materials. 126-19 is formulated to have exceptional shelf stability compared to most one part heat curing systems.

TYPICAL PROPERTIES:

Property	Value	Units
Viscosity (#TD @ 10 RPM)	55,000 to 70,000	Cps
Volume Resistivity (60 min @ 100°C)	< 0.001	Ω-cm
Volume Resistivity (20 min @ 150°C)	< 0.0005	Ω-cm
Thermal Conductivity	7.0	W/mK
Glass Transition Temperature (Tg)	77	°C
Weight Loss at 300°C	< 3	% wt.
Die Shear Strength, min.	3750	psi
Thixotropic Index	> 5.0	-
Solvent Resistance	Excellent	-
Solderable	No	-
Specific Gravity	3.1	g/cc
Useful Temperature Range	-55 to 200	°C
Thermal Stability	Good to 300	°C
Silver Content	69 to 71	% wt.

SUGGESTED HANDLING AND CURING INSTRUCTIONS: Material is ready to use as received. Remove product from freezer and allow material to warm to room temperature before opening container. Best results are obtained when product is cured at one of the following schedules:

60 min @ 100°C
20 min @ 150°C

STORAGE: Shelf life: > 2 weeks at 25°C; or 6 months at -10°C; or 12 months at -40°C.

SAFETY & HANDLING: Use with adequate ventilation. Keep away from sparks and open flames. Avoid prolonged contact with skin and breathing of vapors. Wash with soap and water to remove from skin.

All technical information is based on data obtained by CMI personnel and is believed to be reliable. No warranty is either implied or expressed with respect to results or possible infringements on patents.

REVISION DATE: 04/29/14 REVISION: B